1	2	3	L	' +	5 6 7 8
		•	•		
ARTING DIN Sig	anal har hi	16 61 mal	a cappactan	RoHS / FR	Soldering instructions
ווכ אווע	ווםו וומוי-טו	15 04 IIIdl	e connector	compliant C 711 US	rs
					The connectors should be protected when being soldered in a dip, flow or film soldering bath. Otherwise, they might become
		-			contaminated as a result of soldering operations or deformed as a result of overheating.
ieneral information	<u>:</u>	÷	÷	:	(1) For prototypes and short runs protect the connectors with an industrial adhesive tape, e.g. Tesaband 4331 (www.tesa.de).
	155 (107() 117				Cover the underside of the connector moulding and the adjacent parts of the pcb as well as the open sides of the connector. The
lesign	IEC 61076-4-113				will prevent heat and gases of the soldering apparatus from damaging the connector. About 140 + 5 mm of the tape should suffice.
o. of contacts	max. 160 2,54mm	,			— Surfice.
ontact spacing est voltage	<u>'</u>	1000V			— (2) For large series a jig is recommended. Its protective cover with a fast action mechanical locking device shields the connectors
ontact resistance		max. 20m0hm for rows a, b, c max. 30m0hm for rows d, z			from gas and heat generated by the soldering apparatus. As an additional protection a foil can be used for covering the parts that should not be soldered.
nsulation resistance		min. 10 ¹² Ohm			— That should not be soldered.
orking current		1A at 70°C (see derating diagram)			Cross section of solder pins
emperature range	-55°C +125°C				
ermination technology	solder	,		,	Recommended plated hole diameter: Ø 1± 0,1mm
· · · · · · · · · · · · · · · · · · ·		minimum distar	nce rows a, b, c	rows d, z	<u> </u>
Clearance & creepage	between 2 ro	clearance	1,2mm	1,2mm	Row z: A= 0,21mm² – 0,25mm² Row a, b, c: A= 0,28mm² – 0,33mm² Row d: A= 0,29mm² – 0,33mm²
	DETWEEN Z TO	ws creepage	1,2mm	1,2mm	
	between 2		1,2mm	1,0mm	0,49*0,06
	contacts in a	row creepage	1,2mm	1,0mm	
sertion and withdrawal force	max. 160N				
PCB thickness min. 1,6mm				— l	
Mating cycles acc. to performance level, see table below UL file E102079				— 0,52 ₋₀	
oHS - compliant	Yes	,	,		
eadfree	Yes				
nsulator material	÷	*	÷	-	The current carrying capacity is limited by maximum
					temperature of materials for inserts and contacts including terminals.
1aterial	LCP (Liquid Cristal Polymer)				_
olour	nature				The current capacity curve is valid for continuous, Renow interrupted current loaded contacts of connectors
UL classification UL 94-V0				when simultaneous power on all contacts is given,	
1aterial group acc. to IEC 60664-1	IIIa (175 <u><</u> CTI < 4	.00)			without exceeding the maximum temperature.
					Control and test procedures according to DIN IEC 60512-5
ontact material					─ With selective loading higher currents can be transmitted.
ontact material	Copper alloy				The requirements according to VITA 1.7 are fulfilled. $0.0 + 1 + 1 + 1 + 1 + 1 + 1 + 1 + 1 + 1 + $
Plating termination zone Sn over Ni				Temperature [°C]	
Plating contact zone acc. to performance level, see table below				_	
		· · · · · · · · · · · · · · · · · · ·			
	<u> </u>				<u> </u>
	mating c	vcles	plating cor	ntact zone	_
performance level	1				
parior manage teret	acc. to IEC 61076-4-113 acc	complementary :. to IEC 61076-4-113	row d,z	row a,b,c	
1	500	10 166 01070-4-113	Au over Ni	Au over PdNi over Ni	-
2	250	+	Au over Ni	Au over PdNi over Ni	
3	230	50	Au over Ni	Au over PdNi over Ni	
Au30		500		inch) Au over Ni	
Au50		500	min. 1,27µm (50µi		Att Tights reserved STORCK LEHNERT 302077 2020_11_27 Final Release
	plating ontions highlight		ing options are available or	-	Department EL PD Title Doc-Key / ECM-
310110010	brainid obilona manudin	co in bota, office plat	ייים ספיוטוים מוב מימונמטוב טו		DIN Signal har-bus 64 male connector
					HARTING Electronics GmbH
				1	D-32339 Espelkamp Type DS Number 02011200201 Rev. B

Mouser Electronics

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